

# PATENT ASSIGNMENT

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT										
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Charles W.C. Lin</td> <td>07/28/2010</td> </tr> <tr> <td>Chia-Chung Wang</td> <td>07/28/2010</td> </tr> <tr> <td>Sangwhoo Lim</td> <td>07/28/2010</td> </tr> </tbody> </table>		Name	Execution Date	Charles W.C. Lin	07/28/2010	Chia-Chung Wang	07/28/2010	Sangwhoo Lim	07/28/2010		
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;"><b>Name:</b></td> <td>Bridge Semiconductor Corporation</td> </tr> <tr> <td><b>Street Address:</b></td> <td>3rd Floor, 157 Li-Te Road, Peitou District</td> </tr> <tr> <td><b>City:</b></td> <td>Taipei</td> </tr> <tr> <td><b>State/Country:</b></td> <td>TAIWAN</td> </tr> <tr> <td><b>Postal Code:</b></td> <td>112</td> </tr> </table>		<b>Name:</b>	Bridge Semiconductor Corporation	<b>Street Address:</b>	3rd Floor, 157 Li-Te Road, Peitou District	<b>City:</b>	Taipei	<b>State/Country:</b>	TAIWAN	<b>Postal Code:</b>	112
<b>Name:</b>	Bridge Semiconductor Corporation										
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<b>PROPERTY NUMBERS Total: 1</b>											
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<b>CORRESPONDENCE DATA</b>											
<p>Fax Number: (656)534-8977  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 11-65-6534-8977</p> <p>Email: davidsigmond@hotmail.com</p> <p>Correspondent Name: David M. Sigmond</p> <p>Address Line 1: 10 Anson Road #47-14</p> <p>Address Line 4: Singapore, SINGAPORE 079903</p>											
<b>ATTORNEY DOCKET NUMBER:</b>	BDG061										
<b>NAME OF SUBMITTER:</b>	David M. Sigmond										
<p>Total Attachments: 1          source=Assignment#page1.tif</p>											

CH \$40.00 12848175

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**PATENT**  
**REEL: 024771 FRAME: 0349**

## ASSIGNMENT

WHEREAS, we, CHARLES W.C. LIN of Singapore, CHIA-CHUNG WANG of Taiwan and SANGWHOO LIM of Malaysia have invented a certain new and useful invention entitled SEMICONDUCTOR CHIP ASSEMBLY WITH POST/BASE HEAT SPREADER AND CERAMIC BLOCK IN POST, for which an application for Letters Patent of the United States has been prepared for filing, said application being identified as Attorney Docket No. BDG061;

NOW THEREFORE, be it known that we, the said inventors, for and in consideration of certain good and valuable consideration, the sufficiency and receipt of which is hereby acknowledged, at the request of the assignee do sell, assign and transfer unto said assignee, BRIDGE SEMICONDUCTOR CORPORATION, a Taiwan Corporation having a place of business at 3<sup>rd</sup> Floor, 157 Li-Te Road, Peitou District, Taipei, Taiwan 112, its successors, legal representatives and assigns, the aforesaid application for the territory of the United States of America and all continuation, divisional, continuation-in-part and reissue applications, all patent applications in foreign countries, all applications pursuant to the Patent Cooperation Treaty, and all applications for extension filed or to be filed for the invention, and all Letters Patent, Invention Registrations, Utility Models, Extensions or Reissues, Reexaminations and other patent rights, obtained for the invention in the United States or any other country; we also assign any right, title or interest in and to the invention which has not already been transferred to the assignee; we warrant that we have made no assignment of the invention, application or patent therefor to a party other than BRIDGE SEMICONDUCTOR CORPORATION and we are under no obligation to make and shall not make any assignment of the invention, application, or patent therefor to any other party; and we further agree to cooperate with the assignee hereunder in obtaining, sustaining and enforcing of any and all such Letters Patent and patent rights and in confirming the assignee's exclusive ownership of the invention, without further consideration, but at the expense of said assignee.

The Commissioner of Patents is hereby authorized and requested to issue the Letters Patent solely in accordance with the terms of this Assignment to BRIDGE SEMICONDUCTOR CORPORATION, its successors, legal representatives and assigns, as the assignee of the entire right, title and interest therein.

IN WITNESS WHEREOF, the parties hereto have executed this Assignment as of the date indicated hereunder.

Date: July 28, 2010 By: [Signature]  
CHARLES W.C. LIN

Date: July 28, 2010 By: [Signature]  
CHIA-CHUNG WANG

案號 : 001018 日期: JUL 28 2010  
Case No. : 001018 Date: JUL 28 2010

本文件之簽名或蓋章在臺灣士林區法院公證處認證。  
Date: 2010.7.28 By: [Signature]

Attested at the Notary Public Office of Taiwan  
Shilin District Court, R.O.C., that the  
signature(s)/seal(s) in this document is/are  
authentic.

Notary Public

Lien, Meng-han

SANGWHOO LIM

-1-

PATENT

RECORDED: 08/04/2010

REEL: 024771 FRAME: 0350